N-Channel Power MOSFET 60 V, 20 A, 39 m Ω

Features

- Low R_{DS(on)}
- High Current Capability
- 100% Avalanche Tested
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V _{DSS}	60	V
Gate-to-Source Voltag	e – Contir	nuous	V_{GS}	±20	٧
Gate-to-Source Voltage - Non-Repetitive (t _p < 10 μs)			V_{GS}	±30	٧
Continuous Drain	in $T_C = 25^{\circ}C$ I_D		I _D	20	Α
Current (R _{θJC})	Steady	T _C = 100°C		13	
Power Dissipation ($R_{\theta JC}$)	State	T _C = 25°C	P_{D}	36	W
Pulsed Drain Current	Pulsed Drain Current $t_p = 10 \mu s$			76	Α
Operating Junction and Storage Temperature			T _J , T _{stg}	-55 to 150	°C
Source Current (Body Diode)			I _S	20	Α
Single Pulse Drain-to-Source Avalanche Energy (V_{DD} = 50 V, V_{GS} = 10 V, R_{G} = 25 Ω , $I_{L(pk)}$ = 19 A, L = 0.1 mH, T_{J} = 25°C)			E _{AS}	18	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T _L	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case (Drain)	$R_{\theta JC}$	3.5	°C/W
Junction-to-Ambient - Steady State (Note 1)	$R_{\theta JA}$	45	

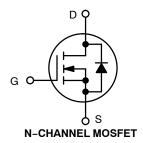
^{1.} Surface-mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [2 oz] including traces.



ON Semiconductor®

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V _{(BR)DSS}	(BR)DSS R _{DS(on)} MAX			
60 V	39 mΩ @ 10 V	20 A		
	50 mΩ @ 4.5 V	18 A		



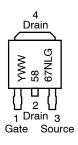


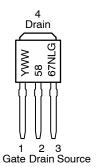
DPAK
CASE 369AA
(Surface Mount)
STYLE 2



IPAK
CASE 369D
(Straight Lead)
STYLE 2

MARKING DIAGRAMS & PIN ASSIGNMENT





Y = Year

WW = Work Week

5867NL = Device Code

G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•					•	
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$		60			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				60		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	Voc = 0 V	T _J = 25°C			1.0	μΑ
		$V_{GS} = 0 V$, $V_{DS} = 60 V$	T _J = 125°C			100	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V				±100	nA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$	= 250 μΑ	1.5	1.8	2.5	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				5.2		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V_{GS} = 10 V, I_D	= 10 A		26	39	mΩ
		V _{GS} = 4.5 V, I _E	₎ = 10 A		33	50	1
Forward Transconductance	9FS	V _{DS} = 15 V, I _D	= 10 A		8.0		S
CHARGES, CAPACITANCES AND GATE RE	SISTANCES						
Input Capacitance	C _{iss}				675		pF
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V, f} = 1$ $V_{DS} = 25$	I.0 MHz, V		68		1
Reverse Transfer Capacitance	C _{rss}	v _{DS} = 25 v			47		1
Total Gate Charge	Q _{G(TOT)}				15		nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 10 V, V _{DS} = 48 V, I _D = 20 A			1.0		1
Gate-to-Source Charge	Q _{GS}				2.2		
Gate-to-Drain Charge	Q_{GD}				4.3		
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 4.5 \text{ V}, V_{DS} = 48 \text{ V},$ $I_D = 20 \text{ A}$			7.6		nC
Gate Resistance	R_{G}				1.3		Ω
SWITCHING CHARACTERISTICS (Note 3)						•	
Turn-On Delay Time	t _{d(on)}				6.5		ns
Rise Time	t _r	V_{GS} = 10 V, V_{D}	n = 48 V.		12.6		1
Turn-Off Delay Time	t _{d(off)}	$I_D = 20 \text{ A}, R_G$	= 2.5 Ω		18.2		
Fall Time	t _f				2.4		
DRAIN-SOURCE DIODE CHARACTERISTIC	S					•	
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 V,$	$T_J = 25^{\circ}C$		0.87	1.2	V
		$I_{S} = 10 \text{ A}$ $T_{J} = 100^{\circ}\text{C}$			0.78		1
Reverse Recovery Time	t _{RR}	V_{GS} = 0 V, dls/dt = 100 A/ μ s, I_{S} = 20 A			17		ns
Charge Time	ta				13		1
Discharge Time	tb				4.0		1
Reverse Recovery Charge	Q _{RR}				12		nC

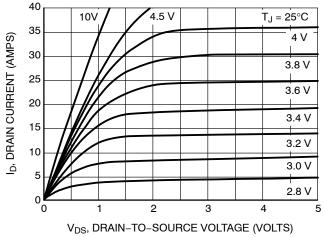
ORDERING INFORMATION

Order Number	Package	Shipping [†]
NTD5867NL-1G	IPAK (Straight Lead) (Pb-Free)	75 Units / Rail
NTD5867NLT4G	DPAK (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

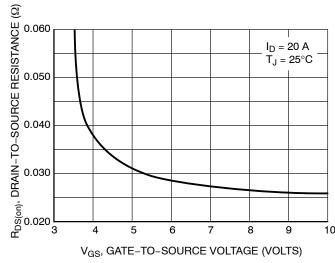
TYPICAL PERFORMANCE CURVES



40 $V_{DS} \ge 10 \text{ V}$ 35 **DRAIN CURRENT (AMPS)** 30 25 20 15 $T_J = 125^{\circ}C$ 10 $T_J = 25^{\circ}C$ Õ $T_J = -55^{\circ}C$ 0<u>L</u> 3 5 V_{GS}, GATE-TO-SOURCE VOLTAGE (VOLTS)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



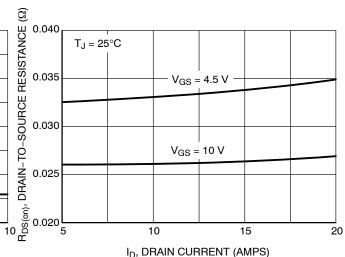
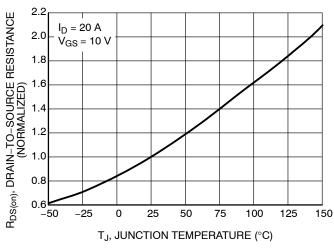


Figure 3. On-Resistance vs. Gate-to-Source Voltage

Figure 4. On-Resistance vs. Drain Current and Gate Voltage



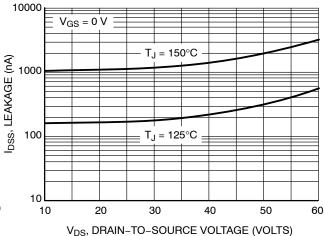


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Drain Voltage

TYPICAL PERFORMANCE CURVES

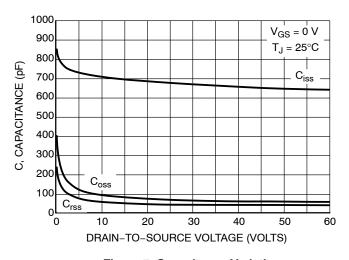


Figure 7. Capacitance Variation

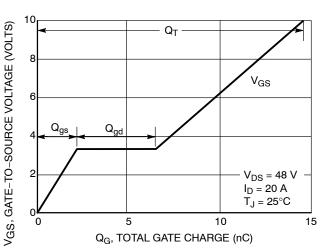


Figure 8. Gate-To-Source Voltage vs.
Total Charge

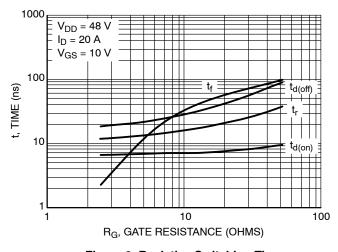


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

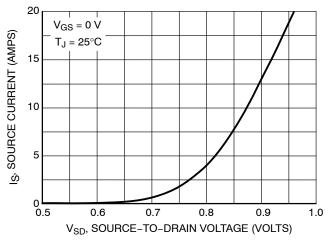


Figure 10. Diode Forward Voltage vs. Current

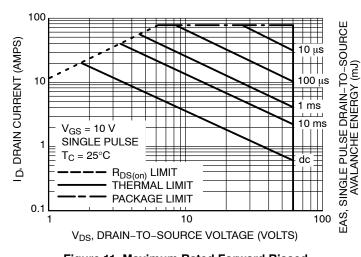


Figure 11. Maximum Rated Forward Biased Safe Operating Area

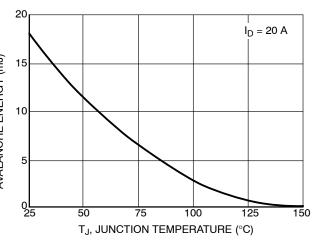


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

TYPICAL PERFORMANCE CURVES

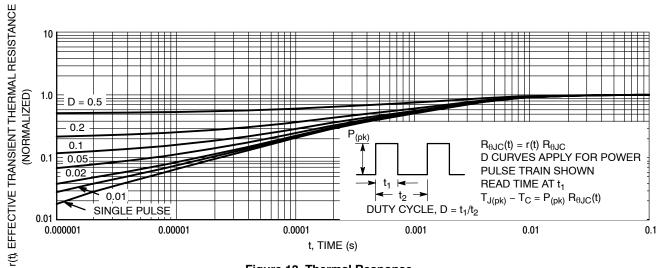
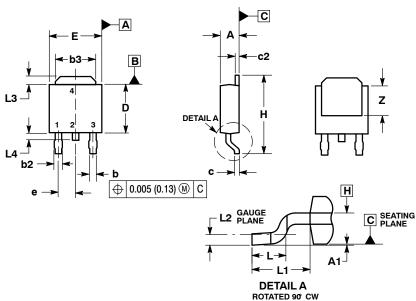


Figure 13. Thermal Response

PACKAGE DIMENSIONS

DPAK (SINGLE GUAGE)

CASE 369AA **ISSUE B**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

 2. CONTROLLING DIMENSION: INCHES.

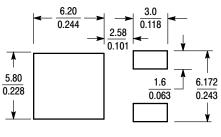
 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3 and Z.

 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.

 5. DIMENSIONS D AND F ARE DETERMINED AT THE
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
 DATUMS A AND B ARE DETERMINED AT DATUM
- PLANE H.

	INC	HES	MILLIMETERS			
DIM	MIN MAX		MIN	MAX		
Α	0.086	0.094	2.18	2.38		
A1	0.000	0.005	0.00	0.13		
b	0.025	0.035	0.63	0.89		
b2	0.030	0.045	0.76	1.14		
b3	0.180	0.215	4.57	5.46		
С	0.018	0.024	0.46	0.61		
c2	0.018	0.024	0.46	0.61		
D	0.235	0.245	5.97	6.22		
Е	0.250	0.265	6.35	6.73		
е	0.090	BSC	2.29 BSC			
Н	0.370	0.410	9.40	10.41		
L	0.055	0.070	1.40	1.78		
L1	0.108	REF	2.74 REF			
L2	0.020	BSC	0.51	0.51 BSC		
L3	0.035	0.050	0.89	1.27		
L4		0.040		1.01		
Z	0.155		3.93			
STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN						

SOLDERING FOOTPRINT*



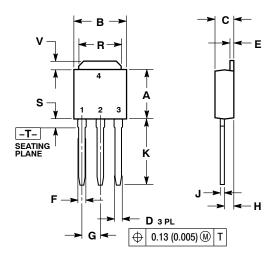
 $\left(\frac{\text{mm}}{\text{inches}}\right)$ SCALE 3:1

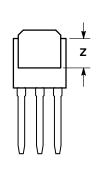
^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

IPAK (STRAIGHT LEAD DPAK)

CASE 369D **ISSUE C**





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.

	INCHES		MILLIM	ETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.235	0.245	5.97	6.35	
В	0.250	0.265	6.35	6.73	
С	0.086	0.094	2.19	2.38	
D	0.027	0.035	0.69	0.88	
Е	0.018	0.023	0.46	0.58	
F	0.037	0.045	0.94	1.14	
G	0.090 BSC		2.29 BSC		
Н	0.034	0.040	0.87	1.01	
J	0.018	0.023	0.46	0.58	
K	0.350	0.380	8.89	9.65	
R	0.180	0.215	4.45	5.45	
S	0.025	0.040	0.63	1.01	
V	0.035	0.050	0.89	1.27	
Z	0.155		3.93		

STYLE 2:

GATE

- 2. DRAIN
- 3. SOURCE
- DRAIN

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